

General Description

The WSD50P10DN56 is the highest performance trench P-ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The WSD50P10DN56 meet the RoHS and Green Product requirement,100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

Product Summery

BVDSS	RDSON	ID
-100V	40mΩ	-34A

Applications

• Power Management for Industrial DC / DC Converters.

DFN5X6 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage -100		V
V _{GS}	Gate-Source Voltage	±20	V
I₀@T₀=25℃	Continuous Drain Current, -V _{GS} @ -10V	-34	А
I _D @T _C =100℃	Continuous Drain Current, -V _{GS} @ -10V	-22	А
I _{DM}	Pulsed Drain Current	-136ª	А
E _{AS} c	Single Pulse Avalanche Energy	Single Pulse Avalanche Energy182Avalanche Current-27	
I _{AS} ^c	Avalanche Current		
P₀@T₀=25℃	PD@Tc=25°CTotal Power Dissipation96TSTGStorage Temperature Range-55 to 150TJOperating Junction Temperature Range-55 to 150		W
T _{STG}			°C
TJ			°C

Thermal Data

Symbol	Parameter Typ. Ma		Max.	Unit	
R _{θJA} ^b	Thermal Resistance Junction-Ambient		60	°C/W	
R _{θJC}	Thermal Resistance Junction-Case		1.3	°C/W	

Note a : Pulse width is limited by max. junction temperature.

Note b : Surface Mounted on $1in^2$ pad area.

Note c : UIS tested and pulse width are limited by maximum junction temperature 150° C(initial temperature T_J= 25° C).



WSD50P10DN56

P-Ch MOSFET

Electrical Characteristics (T_J=25 ~ \odot , unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} =0V , I _D =-250uA	-100			V	
$\triangle BV_{DSS} / \triangle T_J$	BV _{DSS} Temperature Coefficient	Reference to 25 $^\circ\!{\rm C}$, I_D=-1mA		-0.021		V/℃	
Provound	R _{DS(ON)} ^d Static Drain-Source On-Resistance	V _{GS} =-10V , I _D =-18A		32	40	- mΩ	
I DS(ON)		V _{GS} =-4.5V , I _D =-10A		38	51		
V _{GS(th)}	Gate Threshold Voltage		-1.0	-2.0	-3.0	V	
$ riangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{\rm GS} = V_{\rm DS}$, $I_{\rm D} = -2500$ A		4.08		mV/℃	
1	Drain Source Lookage Current	e Current V _{DS} =-80V , V _{GS} =0V , T _J =25 [°] C V _{DS} =-80V , V _{GS} =0V , T _J =85 [°] C	V _{DS} =-80V , V _{GS} =0V , T _J =25℃			-1	
I _{DSS}	Drain-Source Leakage Current				-30 uA		
I _{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm20V$, $V_{DS}=0V$			±100	nA	
Qg ^e	Total Gate Charge			56			
Qgs ^e	Gate-Source Charge	V _{DS} =-30V , V _{GS} =-10V , I _D =-18A		9.5		nC	
Q _{gd} e	Gate-Drain Charge			14.5			
T _{d(on)} e	Turn-On Delay Time			17			
Tre	Rise Time	V_{DD} =-30V , V_{GS} =-10V ,		9		20	
T _{d(off)} e	Turn-Off Delay Time	R _G =6Ω, I _D =-1A ,RL=30Ω	83		ns		
T _f e	Fall Time			34			
C _{iss} ^e	Input Capacitance			2480	3207		
C _{oss} ^e	Output Capacitance	V_{DS} =-50V , V_{GS} =0V , f=1MHz		268		рF	
Crss ^e	Reverse Transfer Capacitance			126			

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I _S	Continuous Source Current	VG=VD=0V, Force Current			-18	А
V_{SD}	Diode Forward Voltage	V_{GS} =0V , I_{S} =-18A , T_{J} =25 $^{\circ}$ C			-1.2	V

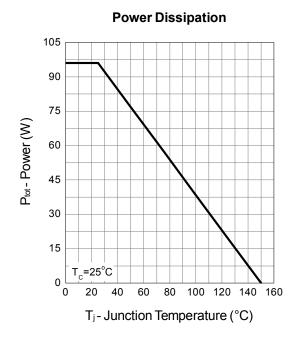
Note d : Pulse test ; pulse width \leq 300µs, duty cycle \leq 2%.

Note e : Guaranteed by design, not subject to production testing.

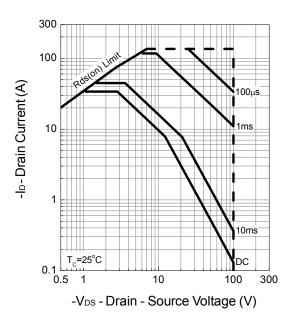




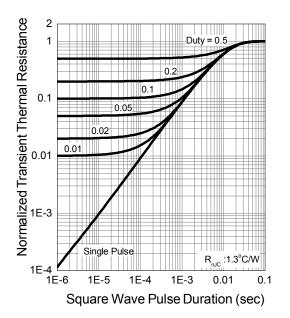
Typical Characteristics



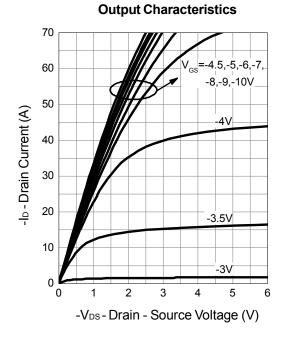
Safe Operation Area



Thermal Transient Impedance





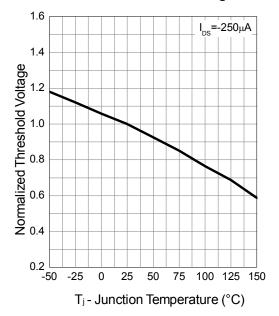


Drain-Source On Resistance

20 10 0 10 20 30 40 50 60 -ID- Drain Current (A)

Gate-Source On Resistance 180 I_{DS}=-18A 150 RDS(ON) - On - Resistance (mQ) 120 90 60 30 0∟ 2 3 4 5 6 7 8 9 10 -VGS - Gate - Source Voltage (V)

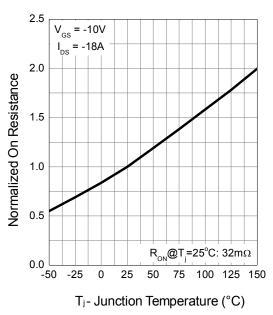
Gate Threshold Voltage



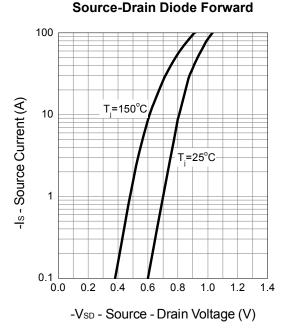


WSD50P10DN56

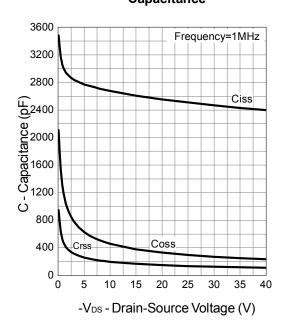
P-Ch MOSFET



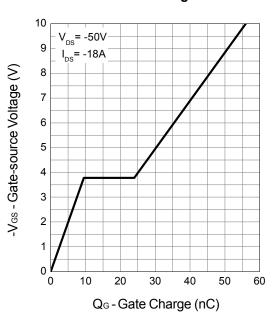
Drain-Source On Resistance



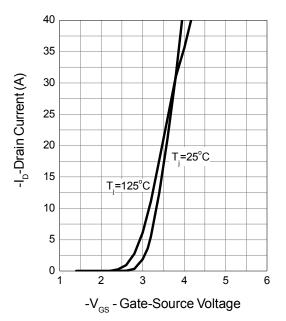
Capacitance



Gate Charge







Transfer Characteristics



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